

amount of the die-bonding film, there is a tendency that the elongation at break of the die-bonding film can be adjusted to be lower. As a result, there is a tendency that the finally obtained die-bonding film is easily divided at the time of expansion since stress is more easily concentrated.

5 The content of the component (D) may be 26% by mass or more or 28% by mass or more on the basis of the total amount of the die-bonding film. The content of the component (D) may be 50% by mass or less, 45% by mass or less, or 40% by mass or less on the basis of the total amount of the die-bonding film. Furthermore, in a case where the die-bonding film

10 contains the component (D), the total content of the component (A), the component (B), and the component (C) may be 75% by mass or less, 74% by mass or less, or 72% by mass or less, and may be 50% by mass or more, 55% by mass or more, or 60% by mass or more, on the basis of the total amount of the die-bonding film.

15 [0054] The mass ratio of the component (D) to the component (C) (the mass of the component (D)/the mass of the component (C)) may be 0.30 or more, 0.35 or more, 0.40 or more, 0.45 or more, or 0.50 or more. When the mass ratio of the component (D) to the component (C) (the mass of the component (D)/the mass of the component (C)) is 0.30 or

20 more, there is a tendency that the elongation at break of the die-bonding film can be adjusted to be low. As a result, there is a tendency that the finally obtained die-bonding film is easily divided at the time of expansion since stress is more easily concentrated. The mass ratio of the component (D) to the component (C) (the mass of the component

25 (D)/the mass of the component (C)) may be, for example, 0.80 or less, 0.70 or less, or 0.60 or less.